Abstract

Method for manufacturing a semiconductor substrate

The invention relates to a method for manufacturing a semiconductor substrate, in particular a semiconductor-on-insulator substrate, comprising the steps of a) providing a donor substrate and a handle substrate, b) forming a pattern of one or more doped regions in, in particular inside, the handle substrate, and then c) attaching, in particular by bonding, the donor and the handle substrate to obtain a donor-handle compound.

Figure 3a